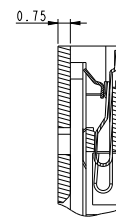
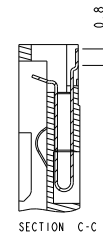
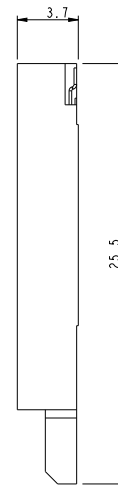
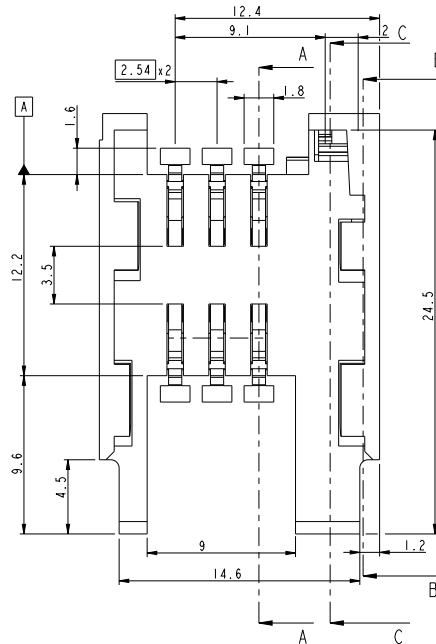
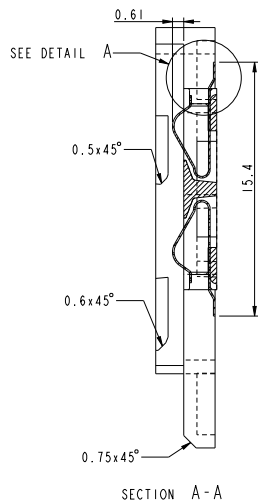
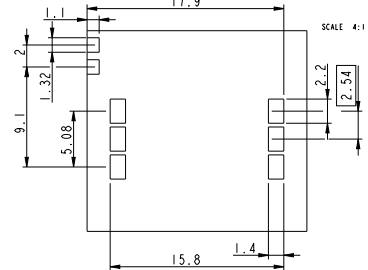
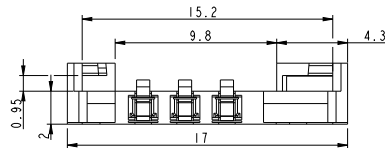
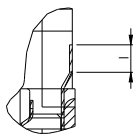


PART NUMBER
LEAD FREE VERSION
7111S1615A02LF

DETAIL A
SCALE 10:1



SECTION B-B
SECTION C-C
CARD
SECTION B-B
SCALE 4:1
DETAIL OF SWITCH

LEAD FREE VERSION:

This product meets European Union Directives and other country regulations as described in GS-22-008

The housing will withstand exposure to 260°C peak temperature for 10 seconds in a convection reflow oven.

PROCESSING

Ni 2 µm
Gold 2.5 µm/Equivalent PdNi over Ni on contact area
Solder tail: Matte tin 2.5 µm (for lead free version)

| rev | | ben no | dr | date | www.fciconnect.com | | surface | | tolerance std | projection | mm |
|-----|----------|--------|-------------|------------|--------------------|-------------|-------------------------------|---------------------------------------|---------------|------------|--------------|
| 01 | - | JB8 | BERNARDET | 1998/09/02 | Eng | ODIC | 1998/09/02 | 150 1302 | 150 406 | 150 1101 | A2 |
| A | - | - | DILIPTHOMAS | 2006/07/18 | Chr | DILIPTHOMAS | 2006/07/18 | TOLERANCES UNLESS OTHERWISE SPECIFIED | | | |
| B | - | MPE | K.V.SIVADAS | 2006/07/18 | Appr | K.V.SIVADAS | 2006/07/18 | ANGULAR | LINEAR | 0.xx | 0 |
| C | LS2025 | MPE | - | 2002-05-04 | Product family | | MOBILE I/O | 0.xxx | ± | ± | Scale |
| D | 105-0167 | NT | - | 2005-09-23 | SPEC ref | | ECN | 0.0xx | ± | ± | 6:1 |
| E | 106-0121 | DTK | - | 2006-07-18 | Product family | | MOBILE I/O | 0.0xx | ± | ± | 109-0291 |
| F | 109-0291 | RKH | - | 2009-12-28 | Product family | | MOBILE I/O | 0.0xx | ± | ± | 109-0291 |
| | | | | | FCI | | SIMCARD CONNECTOR WITH SWITCH | | Rev. | | F |
| | | | | | TYPE S16 | | SPEC ref | | VJW_54479 | | Rev. |
| | | | | | catalog no | | SEE NOTES | | CUSTOMER | | sheet 1 of 1 |

PDM: Rev:F STATUS: Released 8 Printed: Oct 06, 2010